

/ Descriptions

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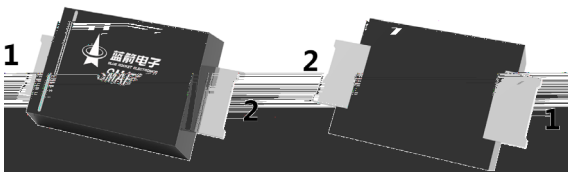
/ Features

/ Applications

/ Equivalent Circuit

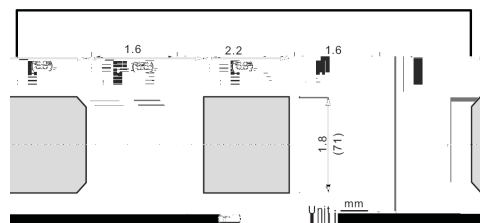


/ Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



/ Marking

**/ Absolute Maximum Ratings(Ta=25 )**

	( )		
			°C
			°C
			°C

)  
)

**/ Electrical Characteristics(Ta=25 )**

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/ Electrical Characteristic Curve

Fig.1. Forward Current Derivation Curve

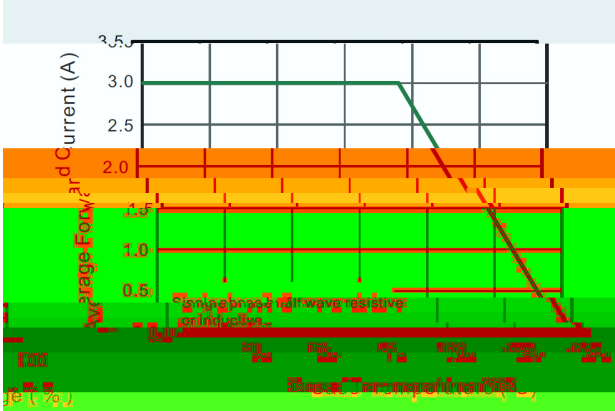


Fig.2. Typical Reverse Current Characteristics

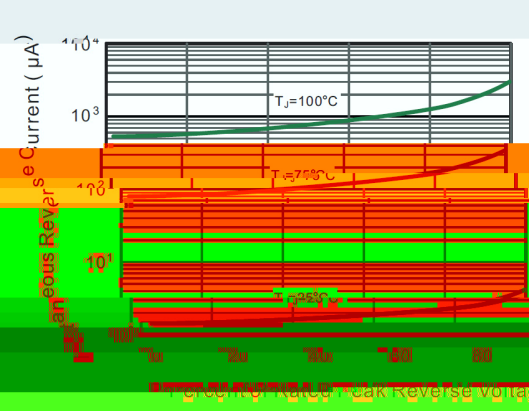


Fig.3. Typical Forward Characteristic

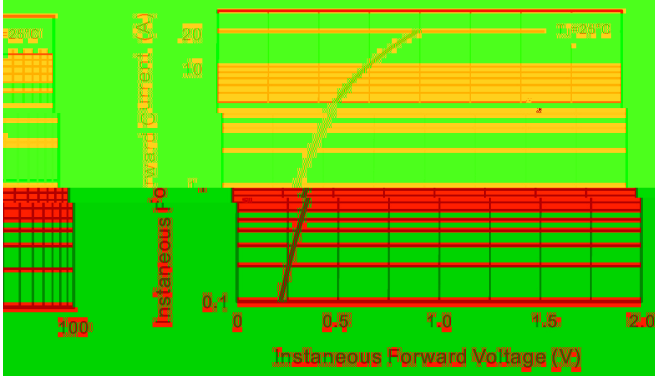


Fig.4. Typical Junction Capacitance

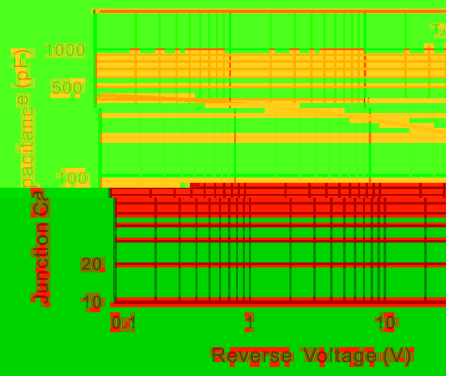


Fig.5. Maximum Non-Repulsive Peak Forward Surge Current

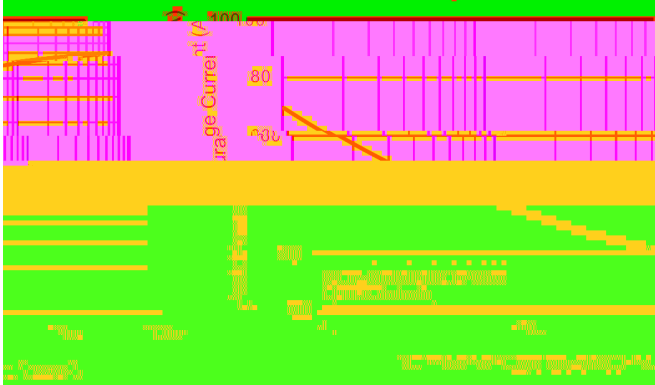
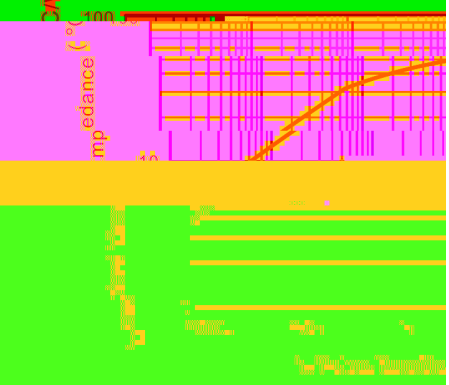
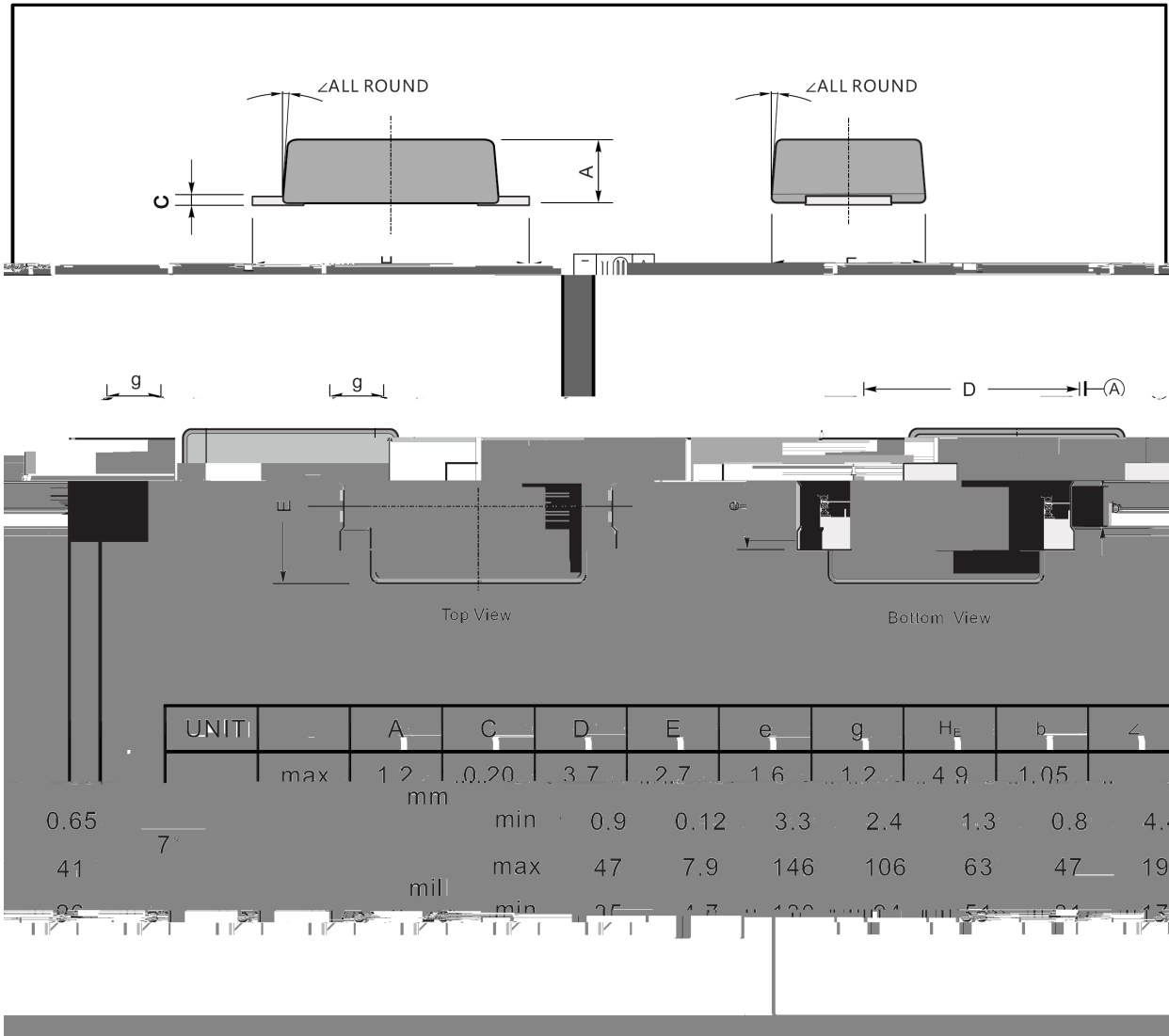


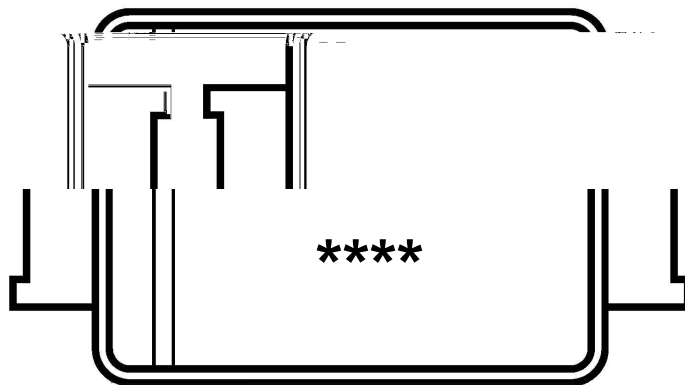
Fig.6. Typical Transient Thermal Impedance



/ Package Dimensions



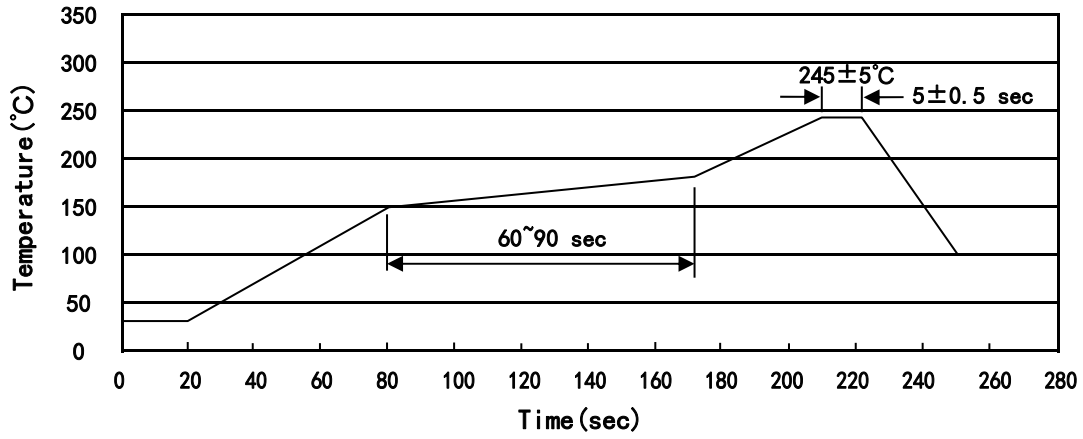
/ Marking Instructions



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( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

/ Packaging SPEC.

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/ Notices